

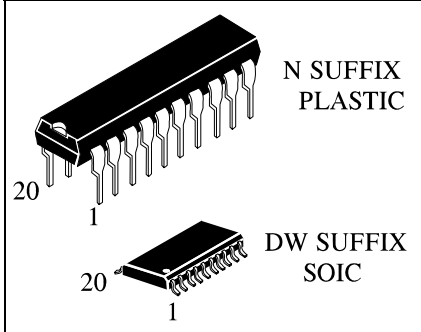
**IN74AC273**

**Octal D Flip-Flop with Common Clock and Reset**

The IN74AC273 is identical in pinout to the LS/ALS273, HC/HCT273. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LS/ALS outputs.

This device consists of eight D flip-flops with common Clock and Reset inputs. Each flip-flop is loaded with a low-to-high transition of the Clock input. Reset is asynchronous and active low.

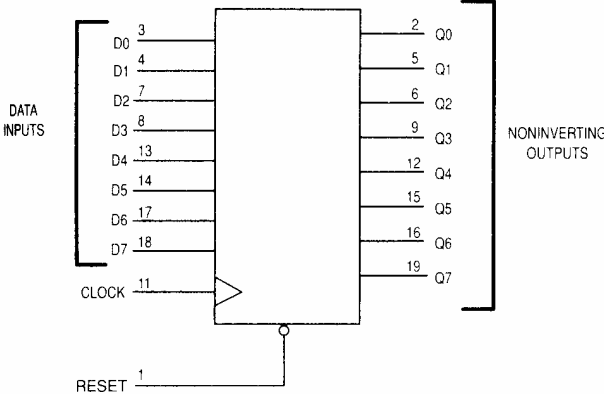
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0  $\mu$ A; 0.1  $\mu$ A @ 25°C
- High Noise Immunity Characteristic of CMOS Devices
- Outputs Source/Sink 24 mA



**ORDERING INFORMATION**

IN74AC273N Plastic  
 IN74AC273DW SOIC  
 IN74AC273DW Chip  
 T<sub>A</sub> = -40° to 85° C for all packages

**LOGIC DIAGRAM**



PIN 20 = V<sub>CC</sub>  
 PIN 10 = GND

**PIN ASSIGNMENT**

RESET	1 ●	20	V <sub>CC</sub>
Q0	2	19	Q7
D0	3	18	D7
D1	4	17	D6
Q1	5	16	Q6
Q2	6	15	Q5
D2	7	14	D5
D3	8	13	D4
Q3	9	12	Q4
GND	10	11	CLOCK

**FUNCTION TABLE**

Inputs			Output
Reset	Clock	D	Q
L	X	X	L
H		H	H
H		L	L
H	L	X	no change
H		X	no change

X = don't care

**MAXIMUM RATINGS\***

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
V <sub>OUT</sub>	DC Output Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IN</sub>	DC Input Current, per Pin	±20	mA
I <sub>OUT</sub>	DC Output Sink/Source Current, per Pin	±50	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA
P <sub>D</sub>	Power Dissipation in Still Air, Plastic DIP** SOIC Package**	750 500	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

\*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

\*\*Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C  
SOIC Package: : - 7 mW/°C from 65° to 125°C

**RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	2.0	6.0	V	
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V	
T <sub>J</sub>	Junction Temperature (PDIP)		140	°C	
T <sub>A</sub>	Operating Temperature, All Package Types	-40	+85	°C	
I <sub>OH</sub>	Output Current - High		-24	mA	
I <sub>OL</sub>	Output Current - Low		24	mA	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time * (except Schmitt Inputs)	V <sub>CC</sub> =3.0 V V <sub>CC</sub> =4.5 V V <sub>CC</sub> =5.5 V	0 0 0	150 40 25	ns/V

\* V<sub>IN</sub> from 30% to 70% V<sub>CC</sub>

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>IN</sub> and V<sub>OUT</sub> should be constrained to the range GND ≤ (V<sub>IN</sub> or V<sub>OUT</sub>) ≤ V<sub>CC</sub>.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

**DC ELECTRICAL CHARACTERISTICS**(Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limits		Unit	
				25 °C	-40°C to 85°C		
V <sub>IH</sub>	Minimum High-Level Input Voltage	V <sub>OUT</sub> =0.1 V or V <sub>CC</sub> -0.1 V	3.0	2.1	2.1	V	
			4.5	3.15	3.15		
			5.5	3.85	3.85		
V <sub>IL</sub>	Maximum Low - Level Input Voltage	V <sub>OUT</sub> =0.1 V or V <sub>CC</sub> -0.1 V	3.0	0.9	0.9	V	
			4.5	1.35	1.35		
			5.5	1.65	1.65		
V <sub>OH</sub>	Minimum High-Level Output Voltage	I <sub>OUT</sub> ≤ -50 μA	3.0	2.9	2.9	V	
			4.5	4.4	4.4		
			5.5	5.4	5.4		
		*V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>		3.0	2.56		2.46
		I <sub>OH</sub> =-12 mA		4.5	3.86		3.76
I <sub>OH</sub> =-24 mA		5.5	4.86	4.76			
V <sub>OL</sub>	Maximum Low-Level Output Voltage	I <sub>OUT</sub> ≤ 50 μA	3.0	0.1	0.1	V	
			4.5	0.1	0.1		
			5.5	0.1	0.1		
		*V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub>		3.0	0.36		0.44
		I <sub>OL</sub> =12 mA		4.5	0.36		0.44
I <sub>OL</sub> =24 mA		5.5	0.36	0.44			
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	5.5	±0.1	±1.0	μA	
I <sub>OLD</sub>	+Minimum Dynamic Output Current	V <sub>OLD</sub> =1.65 V Max	5.5		75	mA	
I <sub>OHD</sub>	+Minimum Dynamic Output Current	V <sub>OHD</sub> =3.85 V Min	5.5		-75	mA	
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>IN</sub> =V <sub>CC</sub> or GND	5.5	8.0	80	μA	

\* All outputs loaded; thresholds on input associated with output under test.

+Maximum test duration 2.0 ms, one output loaded at a time.

Note: I<sub>IN</sub> and I<sub>CC</sub> @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V<sub>CC</sub>

**AC ELECTRICAL CHARACTERISTICS**( $C_L=50\text{pF}$ , Input  $t_r=t_f=3.0\text{ ns}$ )

Symbol	Parameter	$V_{CC}^*$ V	Guaranteed Limits				Unit
			25 °C		-40°C to 85°C		
			Min	Max	Min	Max	
$f_{\max}$	Maximum Clock Frequency (Figure 1)	3.3 5.0	90 140		75 125		MHz
$t_{PLH}$	Propagation Delay, Clock to Q (Figure 1)	3.3 5.0	4.0 3.0	12.5 9.0	3.0 2.5	14.0 10.0	ns
$t_{PLH}$	Propagation Delay, Clock to Q (Figure 1)	3.3 5.0	4.0 3.0	13.0 10.0	3.5 2.5	14.5 11.0	ns
$t_{PHL}$	Propagation Delay, Reset to Q (Figure 2)	3.3 5.0	4.0 3.0	13.0 10.0	3.5 2.5	14.0 10.5	ns
$C_{IN}$	Maximum Input Capacitance	5.0	4.5		4.5		pF

$C_{PD}$	Power Dissipation Capacitance	Typical @25°C, $V_{CC}=5.0\text{ V}$		pF
		50		

\*Voltage Range 3.3 V is 3.3 V  $\pm$ 0.3 V

Voltage Range 5.0 V is 5.0 V  $\pm$ 0.5 V

**TIMING REQUIREMENTS**( $C_L=50\text{pF}$ , Input  $t_r=t_f=3.0\text{ ns}$ )

Symbol	Parameter	$V_{CC}^*$ V	Guaranteed Limits		Unit	
			25 °C			-40°C to 85°C
			Min	Max		Min
$t_{su}$	Minimum Setup Time, Data to Clock (Figure 3)	3.3 5.0	5.5 4.0	6.0 4.5	ns	
$t_h$	Minimum Hold Time, Data to Clock (Figure 3)	3.3 5.0	0 1.0	0 1.0	ns	
$t_w$	Minimum Pulse Width, Clock (Figure 1)	3.3 5.0	5.5 4.0	6.0 4.5	ns	
$t_w$	Minimum Pulse Width, Reset (Figure 2)	3.3 5.0	5.5 4.0	6.0 4.5	ns	
$t_{rec}$	Minimum Recovery Time, Reset to Clock (Figure 2)	3.3 5.0	3.5 2.0	4.5 3.0	ns	

\*Voltage Range 3.3 V is 3.3 V  $\pm$ 0.3 V

Voltage Range 5.0 V is 5.0 V  $\pm$ 0.5 V

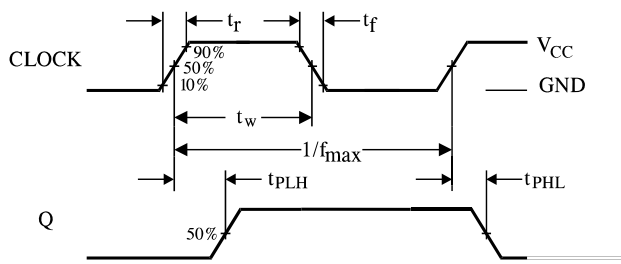


Figure 1. Switching Waveforms

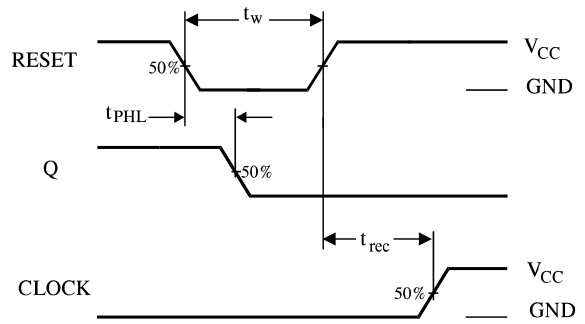


Figure 2. Switching Waveforms

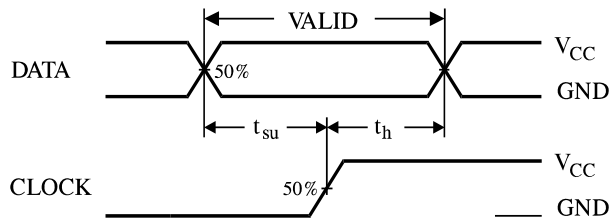
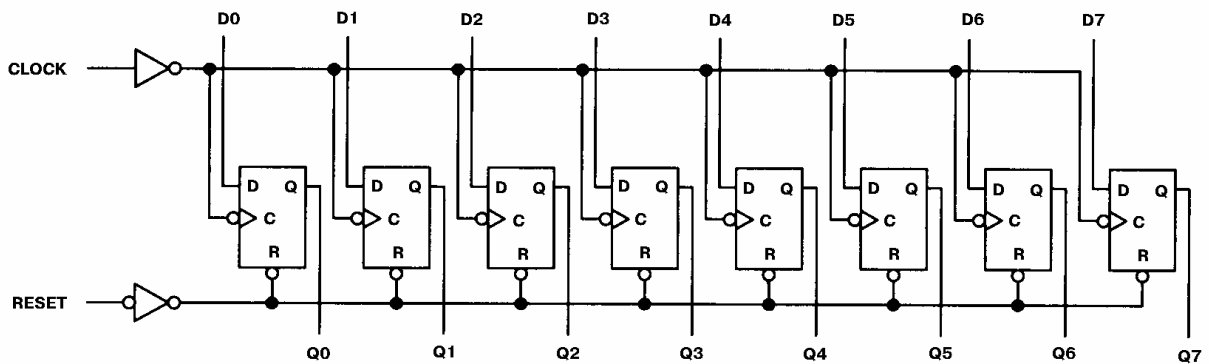
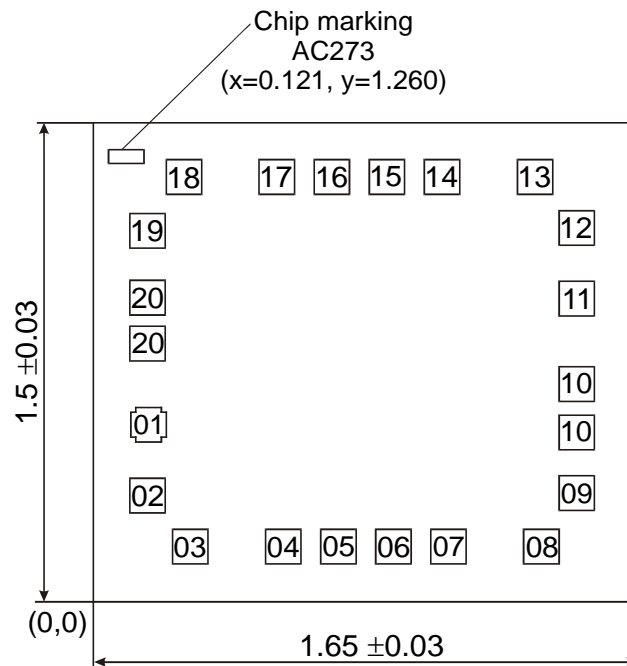


Figure 3. Switching Waveforms

EXPANDED LOGIC DIAGRAM



**PAD CHIP DIAGRAMM IZ74AC273**



Pad size 0.108 x 0.108 mm (Pad size is given as per metallization layer)

Thickness of chip 0,46±0,02 mm

**PAD LOCATION**

Pad No	Symbol	X	Y
01	RESET	0.120	0.507
02	Q0	0.117	0.286
03	D0	0.247	0.127
04	D1	0.531	0.127
05	Q1	0.699	0.127
06	Q2	0.867	0.127
07	D2	1.035	0.127
08	D3	1.318	0.127
09	Q3	1.426	0.294
10	GND	1.426/1.426	0.483/0.570
11	CLOCK	1.428	0.900
12	Q4	1.426	1.120
13	D4	1.299	1.279
14	D5	1.015	1.279
15	Q5	0.847	1.279
16	Q6	0.679	1.279
17	D6	0.511	1.279
18	D7	0.228	1.279
19	Q7	0.117	1.111
20	Vcc	0.117/0.117	0.903/0.816